REMARKS

Reconsideration and allowance, in view of the foregoing amendments and following remarks, are respectfully requested.

Claims 1-17 are currently pending in the application. Claim 1 has been amended. Claims 18-34 were previously withdrawn. Applicants appreciate the allowance of claims 12-17 and the indication that claims 9-11 would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Claim Rejections under 35 U.S.C. § 102

Claims 1-8 stand rejected under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 4,593,384 to Kleijne. Applicants respectfully traverse this rejection.

Independent claim 1, as amended, recites "a sensor comprising at least one conduction path disposed in and integral to at least one of the layers below the first layer of the substrate and at least one conduction path disposed in and integral to at least one of the layers of the cover member." Support for this amendment is found, for example, in the application as filed at page 9, lines 22-24, page 13, lines 1-9, and page 14, lines 15-18.

Kleijne does not disclose or suggest the claimed arrangement in which conduction paths are "disposed in and integral to" the layers of the substrate and the cover member. Rather, Kleijne discloses that the parts P1-P6 are comprised of a ceramic substrate having conductive layers separated by nonconductive or insulating layers, with all layers being deposited on the ceramic

substrate by a conventional screening technique using conventional thick film techniques. (See col.

4, lines 13-22, Fig. 3D.) The disclosed process of assembling the plates P1-P6 is relatively complex,

and involves sequentially screening layers L1, L2, L3 onto the substrate 20 and then forming

electrical connections between the layers L1, L2, L3 at specific points using conductive epoxy. (See

col. 4, line 23 - col. 5, line 51). This is in contrast to the invention of claim 1, in which the

conduction paths are "disposed in and integral to" the layers of the substrate and the cover member.

Accordingly, Applicants respectfully submit that claim 1 is patentable over Kleijne. Claims 2-8

depend from allowable claim 1 and are patentable for the same reasons, as well as for reciting

additional features.

With respect to dependent claim 8, the Examiner stated that "Kleijne discloses each

conduction path comprising a thin-film conductor formed directly on the associated layer," citing to

elements 21, 23, and 24 of figures 3A1, 3B2, and 3C2. Applicants respectfully disagree, and direct

the Examiner's attention to Kleijne at column 4, lines 13-18, where is it expressly stated that "all

layers [are] deposited on the ceramic substrate . . . using conventional thick film techniques." This

is in direct contrast to claim 8, in which "each conduction path compris[es] a thin-film conductor."

Applicants respectfully submit that dependent claim 8 is patentable over Kleijne for this reason, as

well as for the reasons stated above with respect to claim 1.

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Conclusion

All of the stated grounds of objection and rejection have been properly traversed,

accommodated, or rendered moot. Applicants, therefore, respectfully request that the Examiner

reconsider all presently outstanding objections and rejections and that they be withdrawn.

Applicants believe that a full and complete reply has been made to the outstanding Office Action

and, as such, the present application is in condition for allowance. If the Examiner believes, for

any reason, that personal communication will expedite prosecution of this application, the

Examiner is hereby invited to telephone the undersigned at the number provided.

Prompt and favorable consideration of this Amendment is respectfully requested.

Respectfully submitted,

Date: July 6, 2005

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